

DERWENT-ACC- 1995-046385**NO:****DERWENT- 199507****WEEK:****COPYRIGHT 1999 DERWENT INFORMATION LTD****TITLE:** Electroconductive paste providing low resistivity in through holes - includes silver@ and copper@ powders and nitrophenol**PATENT-ASSIGNEE: HITACHI CHEM CO LTD[HITB]****PRIORITY-DATA: 1993JP-0110406 (May 12, 1993)****PATENT-FAMILY:**

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 06325617 A	November 25, 1994	N/A	003	H01B 001/22

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 06325617A	N/A	1993JP-0110406	May 12, 1993

INT-CL (IPC): C09D005/24, H01B001/22 , H05K001/09**ABSTRACTED-PUB-NO: JP 06325617A****BASIC-ABSTRACT:**

Electroconductive paste includes Ag powder, Cu powder and nitrophenol.

The Ag powder is pref. flake or dendrite having an aspect ratio of at least 3 esp. at least 10 and a major dia. of upto 40 microns for maintaining the printability. The Cu powder has a size of upto 20 microns esp. upto 10 microns for dispersing uniformly between the flake Ag powder. The Ag powder and Cu powder are blended in a vol. ratio of 10:1-1:5. The nitrophenol is used in a wt. ratio/solids of 0.05-2.0%. The paste comprises 15-60 (20-60) wt.% Ag and Cu and 85-40 wt.% other ingredients e.g. a fluid organic adhesive, solvent and micropowdery graphite.

ADVANTAGE - The electroconductive paste includes Ag in a smaller amt. and provides low resistivity in through-holes and low degradation in the insulation resistance between through-holes after the wet load test.

CHOSEN- Dwg.0/0**DRAWING:****TITLE-TERMS: ELECTROCONDUCTING PASTE LOW RESISTOR THROUGH HOLE SILVER@ COPPER@ POWDER NITROPHENOL****DERWENT-CLASS: L03 M13 V04 X12****CPI-CODES: L03-A01A3; L03-H04E4; M13-H02;****EPI-CODES: V04-R02P; X12-D01X;****SECONDARY-ACC-NO:**